



[10191/2251]

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inven	tor	(2)
HIVEH	LUI	3

SPITZ et al.

Confirmation No.:

7205

Serial No.

10/070,521

Filed

July 8, 2002

For

ARRANGEMENT HAVING P-DOPED AND N-DOPED SEMICONDUCTOR LAYERS, AND

METHOD FOR THE MANUFACTURE THEREOF

Examiner

J. Jackson

Art Unit

2815

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Atty's Signature

DERVIS MAGISTRE KENYON & KENYON LLP

## **RESPONSE TRANSMITTAL**

SIR:

Please find a Response transmitted herewith for filing in the above-identified patent application.

No fee is believed to be required. However, if any fee is required, please use Deposit Account No. 11-0600. A duplicate copy of this transmittal letter is enclosed for that purpose.

Respectfully submitted,

**KENYON & KENYON LLP** 

Dated: 3/27/bu

B.: LOZ (B. No. 41, 172

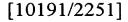
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Inventor(s)

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Atty's Signature **DERVIS MAGISTRE** KENYON & KENYON LLP

## **RESPONSE**

SIR:

In response to the Office Action dated February 13, 2006, reconsideration and allowance of the above-referenced application are requested for the reasons below.

Amendments to the Specification do not appear in this paper.

Amendments to the Claims do not appear in this paper.

Amendments to the Drawings do not appear in this paper.

Remarks begin on page 2 of this paper.